



BES2700IH

Brief Datasheet

Ultra-low Power Bluetooth Audio Platform for TWS, Hybrid ANC and AI Voice Applications

CONTACT US:

Company: Bestechnic (Shanghai) Co., Ltd. (“BES”)

Address: 2F, Building B, Lane 2889 Jinke Road, Pudong, Shanghai (201203)

Phone: (86)21 6877 1788

For product inquiries and more information, please visit www.bestechnic.com.

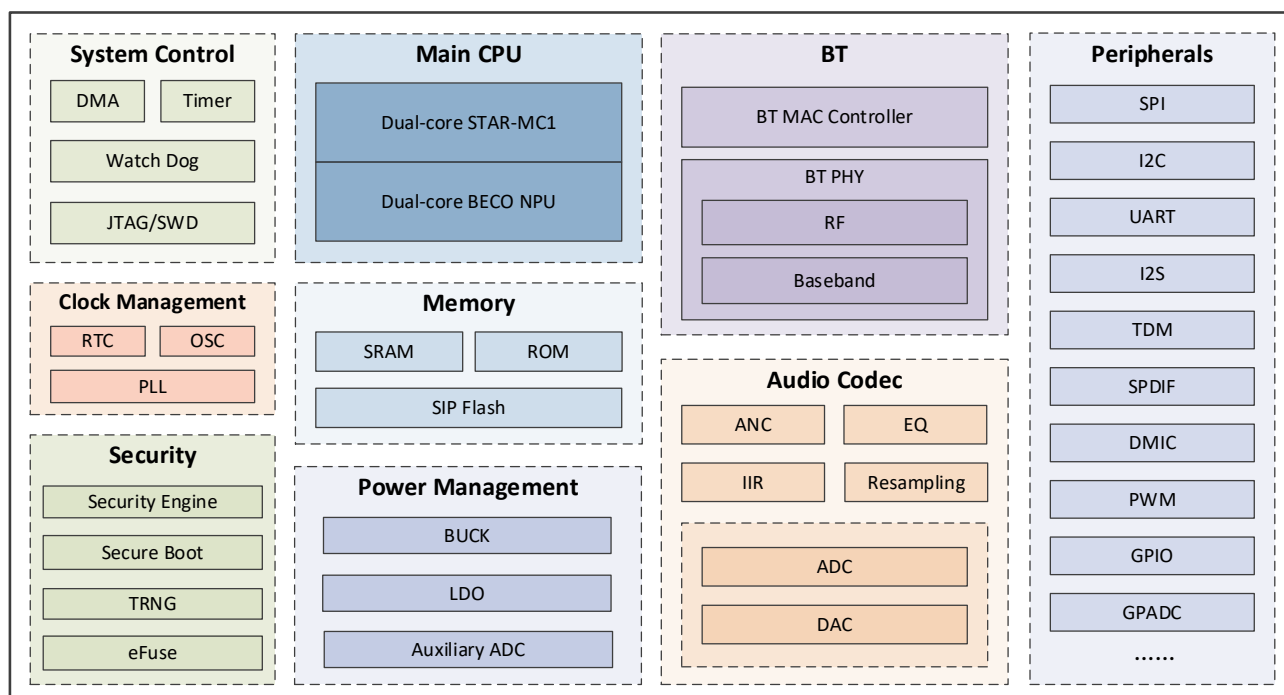
DISCLAIMER:

No part of this document may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, for any purpose, without the express written permission of BES. BES retains the right to make changes to this document at any time, without notice. BES makes no warranty of any kind, expressed or implied, with regard to any information contained in this document, including, but not limited to, the implied warranties of merchant ability or fitness for any particular purpose. Further, BES does not warrant the accuracy or completeness of the information, text, graphics, or other items contained within this document.

1 General Description

The BES2700IH is an ultra-low power Bluetooth audio SoC that integrates a dual-mode Bluetooth 6.1 subsystem and an audio codec subsystem, a high performance CPU subsystem that includes a dual-core STAR-MC1 and a dual-core BECO NPU, a BES proprietary coprocessor for advanced signal processing and NN workloads, RAM/ROM, serial flash for software functions and product customization, and interfaces.

With its highly integrated design and extremely small package size, the BES2700IH is not only suitable for increasingly smaller TWS earbuds applications, but is also ideal for smart rings, where the BES2700IH supports ultra-low power BLE mode.



System Block Diagram

1.1 Applications

- Smart ANC TWS earbuds
- Smart rings
- Other wearable or portable audio devices

1.2 Features & Specifications*

CPU Subsystem	Dual-core STAR-MC1
Memory and Storage	Shared 1.4 MB SRAM
	Flash in package
	boot ROM
Bluetooth Subsystem	Dual-mode BT 6.1 with LE audio
Audio & Voice Features	1x DAC
	3x ADCs
Peripheral Interfaces	SPI/I2C/UART/I2S/TDM/SPDIF/DMIC/PWM/GPIO/GPADC.....
Package	120-pin BGA

* The content in the table is subject to change without notice.